

IN THE CLAIMS:

Claims 10 and 15 were previously cancelled. Claims 1-6, 8, 9,11-14 and 16-21 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Currently amended) A semiconductor device, comprising:
at least one bond pad positioned on a surface of a semiconductor die adjacent an edge thereof;
and
a layer comprising polymer on at least a portion of ~~said~~ the surface, ~~said~~ the layer having a notch formed therein which exposes at least a portion of ~~said~~ the at least one bond pad.
2. (Currently amended) The semiconductor device of claim 1, wherein an edge portion of ~~said~~ the layer adjacent ~~said~~ the edge of ~~said~~ the semiconductor die tapers from a surface of ~~said~~ the layer toward ~~said~~ the edge of ~~said~~ the semiconductor die.
3. (Currently amended) The semiconductor device of claim 2, wherein ~~said~~ the edge portion of ~~said~~ the layer comprises a bevel.
4. (Currently amended) The semiconductor device of claim 1, wherein ~~said~~ the notch is tapered from a surface of ~~said~~ the layer toward ~~said~~ the surface of ~~said~~ the semiconductor die.
5. (Currently amended) The semiconductor device of claim 1, wherein ~~said~~ the layer covers substantially all of ~~said~~ the surface.

6. (Currently amended) The semiconductor device of claim 1, wherein ~~said~~ the notch substantially surrounds ~~said~~ the at least one bond pad.

7. (Previously presented) The semiconductor device of claim 1, including a plurality of bond pads.

8. (Currently amended) The semiconductor device of claim 7, wherein at least some of ~~said~~ the bond pads are located adjacent ~~said~~ the edge.

9. (Currently amended) The semiconductor device of claim 8, wherein ~~said~~ the layer includes regions extending laterally between adjacent bond pads of ~~said~~ the at least some bond pads.

10. (Cancelled)

11. (Currently amended) The semiconductor device of claim 1, wherein ~~said~~ the polymer comprises a photoimageable material.

12. (Currently amended) A protective layer for a semiconductor die, comprising:
a substantially planar member comprising polymer; and
at least one notch formed adjacent an edge of ~~said~~ the substantially planar member, ~~said~~ the at least one notch being configured to expose at least a portion of a corresponding bond pad of the semiconductor die upon positioning the protective layer over an active surface of the semiconductor die.

13. (Currently amended) The protective layer of claim 12, further comprising a bevel along ~~said~~ the edge.

14. (Currently amended) The protective layer of claim 12, wherein at least one edge of ~~said~~ the at least one notch is beveled.

15. (Cancelled)

16. (Currently amended) The protective layer of claim 12, wherein ~~said~~ the polymer comprises a photoimageable material.

17. (Currently amended) The protective layer of claim 12, including a plurality of notches located along ~~said~~ the edge.

18. (Currently amended) The protective layer of claim 12, wherein ~~said~~ the substantially planar member is configured to substantially cover ~~said~~ the active surface of the semiconductor die upon assembly therewith.

19. (Currently amended) The protective layer of claim 12, wherein ~~said~~ the substantially planar member is configured to cover only a portion of a surface of the semiconductor die adjacent an edge thereof proximate to which at least one bond pad is located upon assembly of the protective layer with the semiconductor die.

20. (Currently amended) The protective layer of claim 12, wherein ~~said~~ the at least one notch is formed in ~~said~~ the edge.

21. (Currently amended) The protective layer of claim 12, wherein ~~said~~ the at least one notch is configured to substantially surround the corresponding bond pad upon assembly of the protective layer with the semiconductor die.